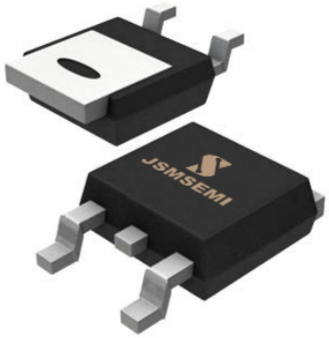
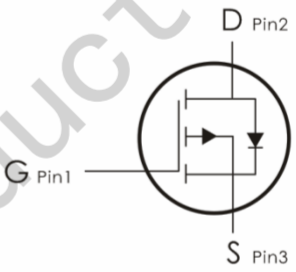
Description：

This P-Channel MOSFET uses advanced trench technology and design to provide excellent $R_{DS(on)}$ with low gate charge.It can be used in a wide variety of applications.



Features：

- V_{DS}=-100V,I_D=-12A,$R_{DS(ON)}$<200mΩ @V_{GS}=-10V
- Low gate charge.
- Green device available.
- Advanced high cell denity trench technology for ultra $R_{DS(ON)}$.
- Excellent package for good heat dissipation.



Absolute Maximum Ratings (T_C=25℃ unless otherwise noted)

Symbol	Parameter	Ratings	Units
V_{DS}	Drain-Source Voltage	-100	V
V_{GS}	Gate-Source Voltage	±20	V
I_D	Continuous Drain Current-1	-12	A
	Continuous DrainCurrent-TC=100℃	-9.2	
	Pulsed Drain Current2	-52	
E_{AS}	Single Pulse Avalanche Energy3	65	mJ
P_D	Power Dissipation4	40	W
T_J, T_{STG}	Operating and Storage Junction Temperature Range	-55 to +150	℃

Thermal Characteristics：

Symbol	Parameter	Max	Units
$R_{\theta JC}$	Thermal Resistance,Junction to Case(Note2)	3.13	℃/W
$R_{\theta JA}$	Thermal Resistance,Junction to Ambient1	---	

Electrical Characteristics (T_C=25℃ unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
Off Characteristics						
BV_{DSS}	Drain-Sourtce Breakdown Voltage	V_{GS}=0V,I_D=250μA	-100	---	---	V
I_{DSS}	Zero Gate Voltage Drain Current	V_{GS}=0V,V_{DS}=-100V	---	---	1	μA
I_{GSS}	Gate-Source Leakage Current	V_{GS}=±20V,V_{DS}=0A	---	---	±10	nA
On Characteristics						
$V_{GS(th)}$	GATE-Source Threshold Voltage	V_{GS}=V_{DS},I_D=250μA	-1	-1.9	-3	V
$R_{DS(ON)}$	Drain-Source On Resistance2	V_{GS}=-10V,I_D=16A	---	170	200	mΩ
		V_{GS}=-4.5V,I_D=A	---	---	---	
G_{FS}	Forward Transconductance	V_{DS}=-50V, I_D=-10A	12	---	---	S
Dynamic Characteristics						
C_{iss}	Input Capacitance	V_{DS}=-25V,V_{GS}=0V, f=1MHz	---	760	---	pF
C_{oss}	Output Capacitance		---	260	---	
C_{rss}	Reverse Transfer Capacitance		---	170	---	
Switching Characteristics						
$t_{d(on)}$	Turn-On Delay Time	V_{DD}=-50V,I_D=10A, R_{GEN}=9.1Ω .V_{GS}=-10V	---	14	---	ns
t_r	Rise Time		---	18	---	ns
$t_{d(off)}$	Turn-Off Delay Time		---	50	---	ns
t_f	Fall Time		---	18	---	ns
Q_g	Total Gate Charge	V_{GS}=-10V,V_{DS}=-50V, I_D=-10A	---	25	---	nC
Q_{gs}	Gate-Source Charge		---	5	---	nC
Q_{gd}	Gate-Drain " Miller" Charge		---	7	---	nC
Drain-Source Diode Characteristics						
V_{SD}	Source-Drain Diode Forward Voltage2	V_{GS}=0V,Is=10A	---	---	-1.2	V
Is	Diode ForwardCurrent(Note2)	VD=VG=0V	---	---	-13	A
Trr	Reverse Recovery Time	TJ = 25°C, IF =-10A di/dt = 100A/s(Note3)	---	35	---	nS
Qrr	Reverse Recovery Charge		---	46	---	nC

Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board, t ≤ 10 sec.
3. Pulse Test: Pulse Width ≤ 300μs, Duty Cycle ≤ 2%.
4. Guaranteed by design, not subject to production
5. E_{AS} condition：Tj=25℃,V_{DD}=-50V,V_G=-10V,L=0.5mH,Rg=25Ω

Typical Characteristics (T_C=25℃ unless otherwise noted)

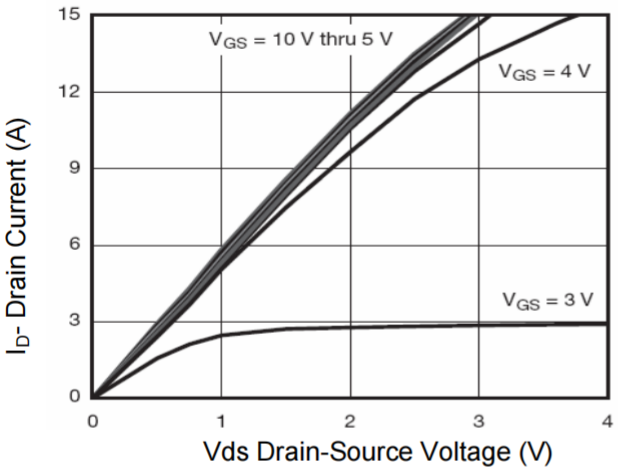


Figure 1 Output Characteristics

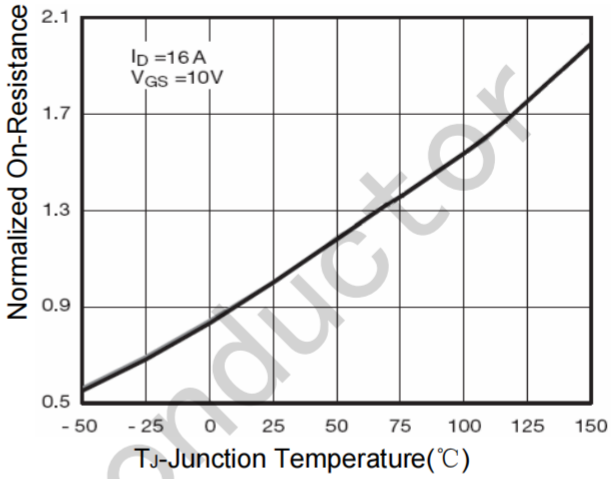


Figure 4 Rdson-JunctionTemperature

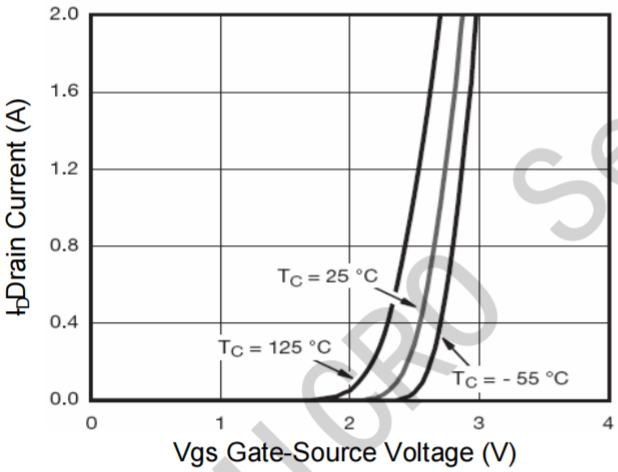


Figure 2 Transfer Characteristics

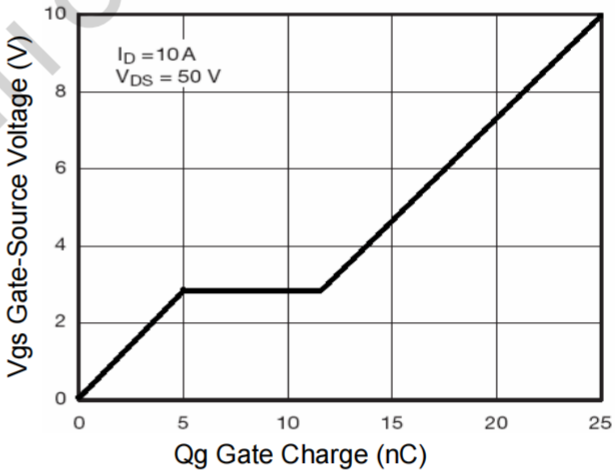


Figure 5 Gate Charge

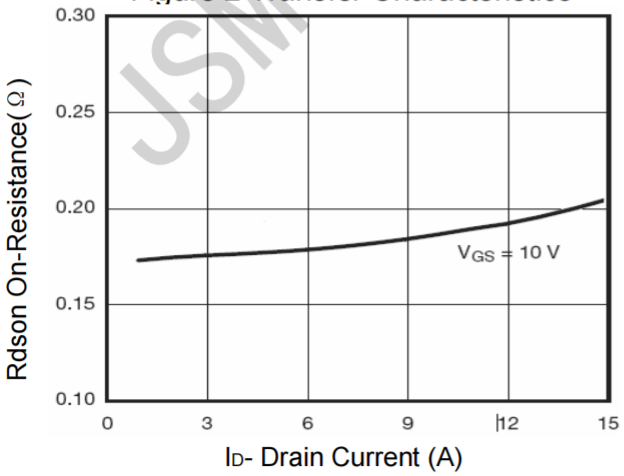


Figure 3 Rdson- Drain Current

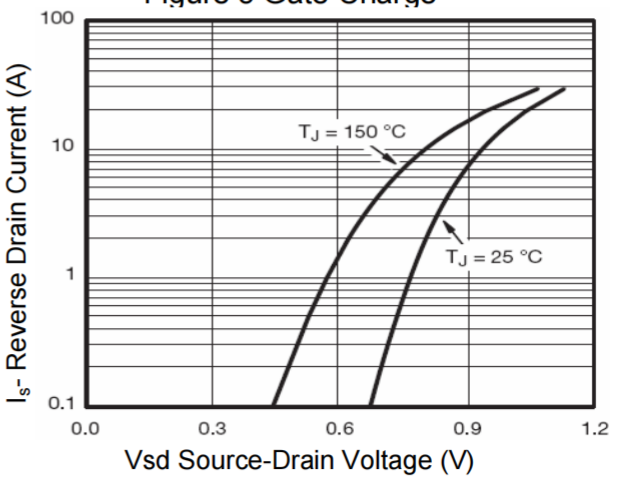


Figure 6 Source- Drain Diode Forward

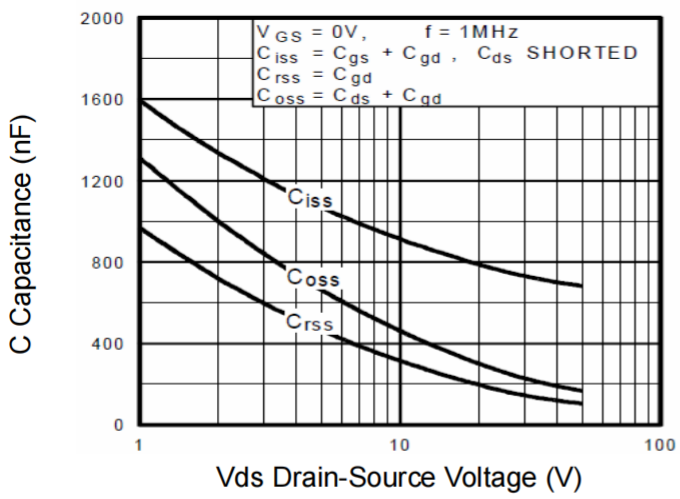
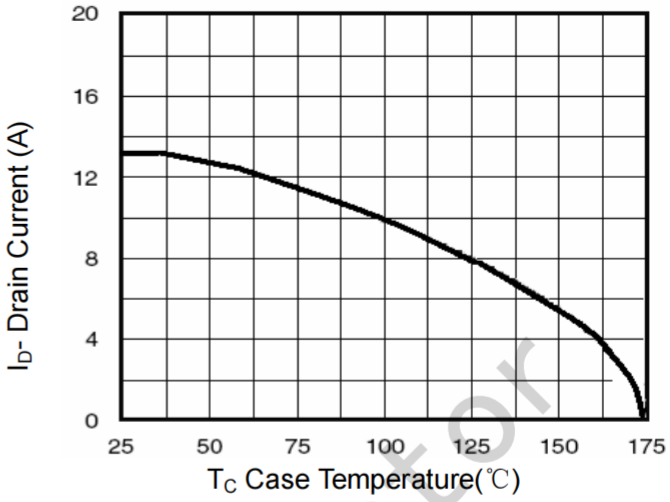


Figure 7 Capacitance vs Vds



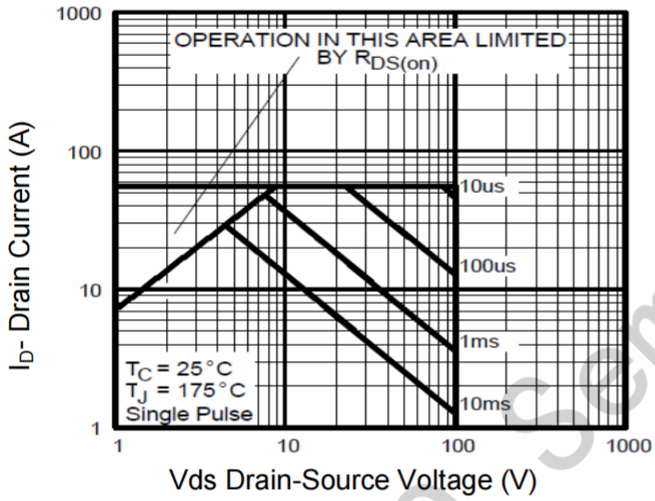


Figure 8 Safe Operation Area

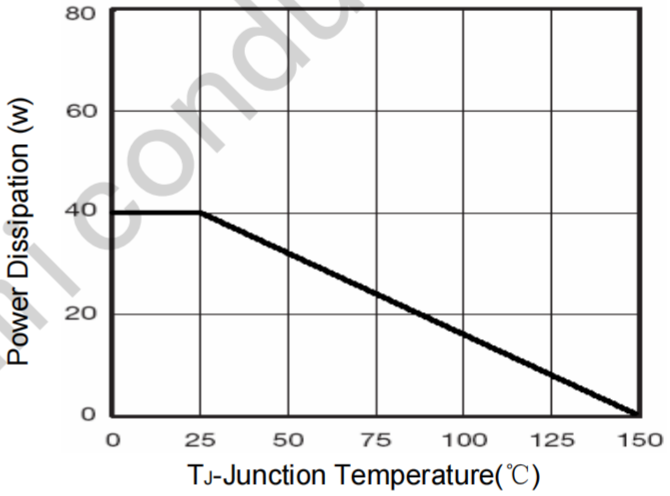


Figure 10 Power De-rating

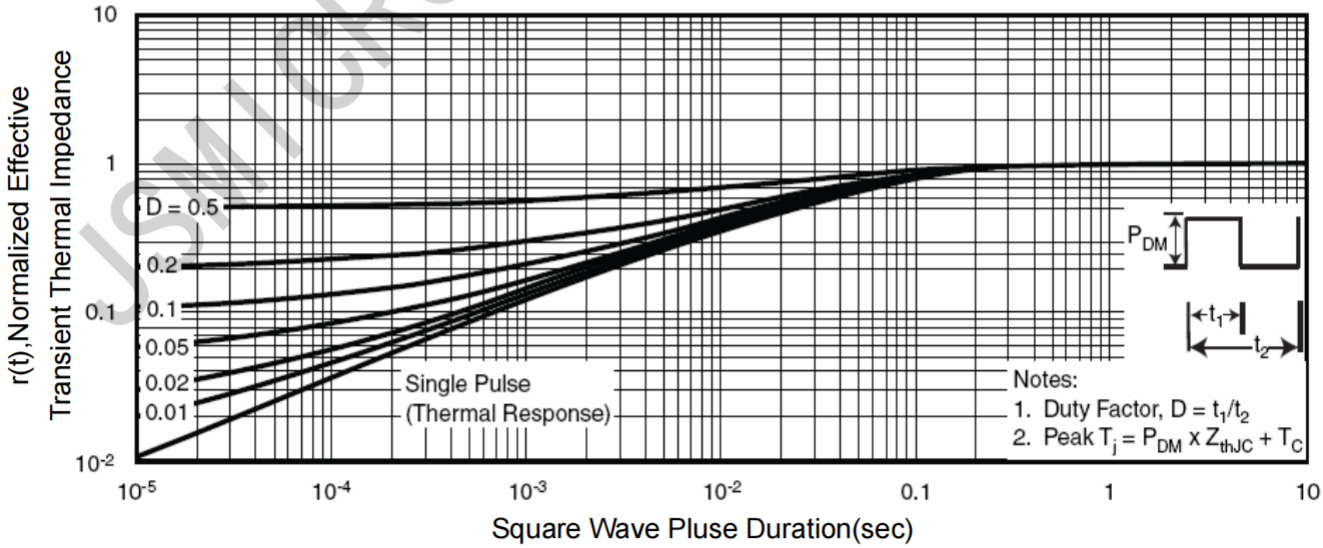
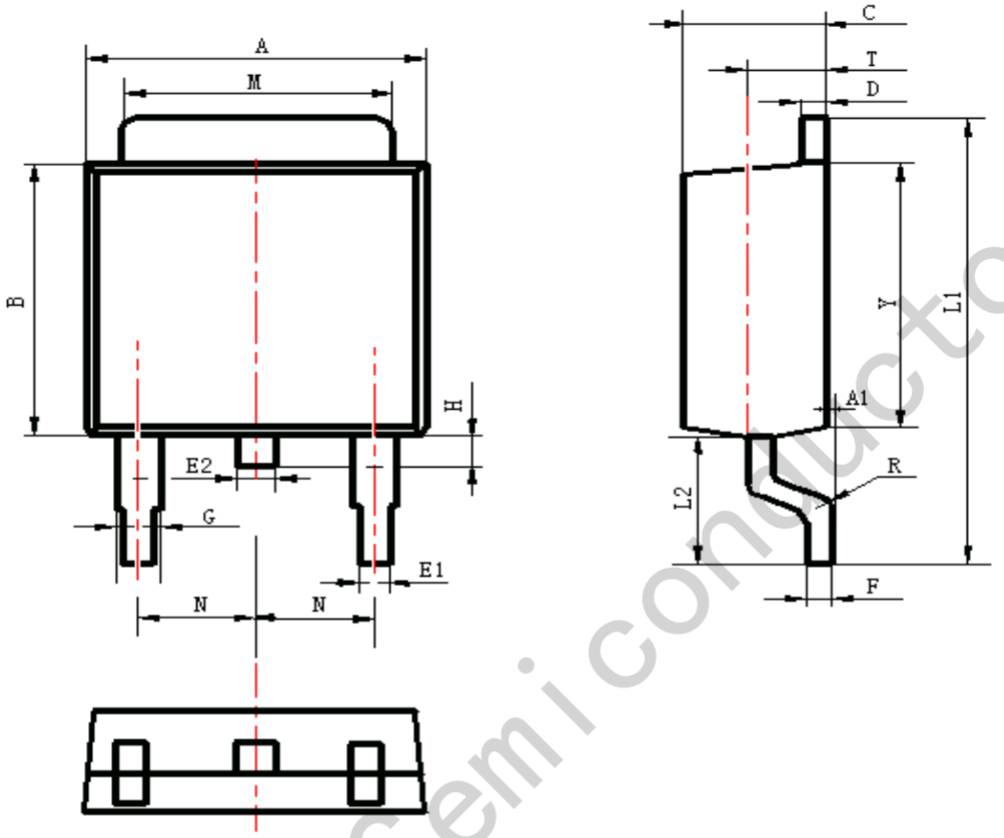


Figure 11 Normalized Maximum Transient Thermal Impedance

Package Information

TO-252



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	6.30	6.90	0.248	0.272
A1	0.00	0.16	0.000	0.006
B	5.70	6.30	0.224	0.248
C	2.10	2.50	0.083	0.098
D	0.30	0.70	0.012	0.028
E1	0.60	0.90	0.024	0.035
E2	0.70	1.00	0.028	0.039
F	0.30	0.60	0.012	0.024
G	0.70	1.20	0.028	0.047
L1	9.60	10.50	0.378	0.413
L2	2.70	3.10	0.106	0.122
H	0.40	1.00	0.016	0.039
M	5.10	5.50	0.201	0.217
N	2.09	2.49	0.082	0.098
R	0.30		0.012	
T	1.40	1.60	0.055	0.063
Y	5.10	6.30	0.201	0.248